

Product Data Sheet

# WS-366 Interconnect Flux

## Benefits

- Excellent cleanability, residue can be removed with room temperature water
- Can be used for printing, dipping, and pin transfer deposition
- Offers high yields in BGA bumping process
- Excellent solderability
- Wide process window
- Suitable for Sn/Pb, Pb-Free, and high lead-containing applications
- Designed for Flip-Chip applications

## Introduction

**WS-366 Interconnect Flux** is a high viscosity paste-type flux designed for use in BGA bumping and board level attachment. It can also be used wherever a water-soluble flux with excellent cleanability is desired.

## Properties

Flux type Classification:	HI
Color:	Amber to brown
Stencil Life:	>8 hours at room temperature
Shelf Life:	6 months at -20°C to +5°C 3 months at +5°C to 25°C
SIR (ohms, post cleaning):	Pass (>10 <sup>9</sup> after 7 days @ 85°C & 85% RH)
Typical Viscosity:	
Brookfield:	425 kcps at 5RPM
Halide Content:	<3% Cl equivalent
Acid Value:	30-50
Tack Strength:	100-400g

All information is for reference only. Not to be used as incoming product specifications.

## Packaging

**WS-366** is available in SEMCO cartridges, 100g jars or 10-150g syringes, however other packaging can be provided to meet specific requirements.

## Cleaning

DI Water or water plus cleaner that is room temperature or higher for >1 minute at >60psi.

## Reflow

Peak reflow temperature should be <350°C in an air or nitrogen atmosphere, with a linear ramp up to 30°C above solidus temperature.



## Storage

**WS-366** syringes and cartridges should be stored tip down at 0-25°C. **WS-366** should be allowed to stand for 4 hours at room temperature before using.

## Technical Support

Indium Corporation's internationally experienced engineers provide in-depth technical assistance to our customers. Thoroughly knowledgeable in all facets of Material Science as it applies to the electronics and semiconductor sectors, Technical Support Engineers provide expert advice in solder properties, alloy compatibility and selection of solder preforms, wire, ribbon and paste. Indium Corporation Technical Support engineers provide Rapid Response to all technical inquiries.

## Material Safety Data Sheets

The MSDS for this product can be found online at <http://www.indium.com/techlibrary/msds.php>

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the

products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices.

Form No. 98101 (A4) R1

[www.indium.com](http://www.indium.com)

[askus@indium.com](mailto:askus@indium.com)

ASIA: Singapore, Cheongju: +65 6268 8678  
 CHINA: Suzhou, Shenzhen, Liuzhou: +86 (0)512 628 34900  
 EUROPE: Milton Keynes, Torino: +44 (0) 1908 580400  
 USA: Utica, Clinton, Chicago: +1 315 853 4900



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